

表面處理-高性能選擇性化學鍍金技術

Final Finishing – High Performance Selective ENIG Technology

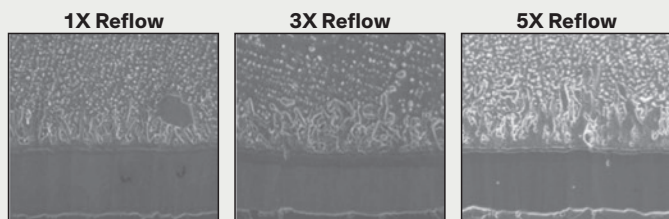


DURAPOSIT™ SMT 820 化學鍍 AUROLECTROLESS™ SMT 520 化學浸金

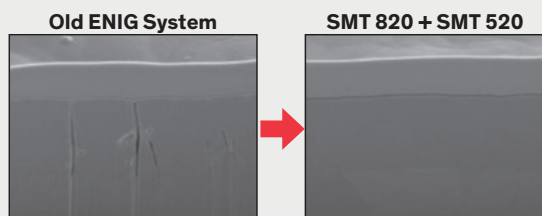
Advantages 優點

- High Ni corrosion resistance without spike observed after 3 times of OSP pass
抗鍍腐蝕能力高可以通過三次OSP後處理而幾乎無“鍍黑牙”
- Capable to pass SO₂ gas corrosion test
能通過SO₂腐蝕測試
- Above 2μ” gold thickness is achievable at low gold content (0.8 g/L)
低金濃度操作下(0.8 g/L)金層可超過2微英寸金層厚度
- Dense gold deposits at high Ni/Cu ion contamination bath condition to ensure good solderability
高鍍銅污染時仍可維持高密度金層而保持良好的可焊性
- Longer gold bath life to reduce running cost saving (12 MTOs) and sustain outstanding gold density and Ni coverage
超長金槽壽命可降低金耗成本,同時仍保有優異的金密度與鍍面覆蓋性
- Excellent solderability for Tin-Lead and Lead free solder joint
對於錫鉛與無鉛焊料具有優異的焊錫性
- No significant performance effect under dry film leaching condition
對乾膜有機物析出不敏感,專用於選擇性化學鍍金製程

多次迴流焊的IMC沒有太大的高低變化,具有優異的可焊性



FIB切片明顯可見三次OSP後沒有鍍腐蝕



經過三次OSP後盲孔上方鍍腐蝕大幅改善SEM圖

